ARTEMIS Call 2013 Project 621429

# EMC<sup>2</sup>



Embedded Multi-Core systems for Mixed Criticality applications in dynamic and changeable real-time environments

## **PROJECT** *description*

EMC<sup>2</sup> finds solutions for dynamic adaptability in open systems. It provides handling of mixed criticality multicore applications in real-time conditions, with scalability and utmost flexibility, full-scale deployment and management of integrated tool chains, through the entire lifecycle.

### **RELEVANCE CALL** 2013 objectives

- >  $EMC^2$  reduces cost of the system design by 15%.
- > It reduces by 15% the effort and time required to re-validate systems after making changes.
- > It achieves 15% reduction in development cycles, especially in sectors requiring qualification or certification.



### **MARKET** innovation

The EMC<sup>2</sup> project expects to facilitate the EU's ability to deploy and use Embedded Systems across important European market sectors:

- > Automotive: Embedded Systems are the key innovation driver, enabling the majority of innovations.
- > Avionics: main challenges are related to the acceleration of technology cycles and cost of software development.
- > Space: main challenges are related to the increase of performance/weight ratio, high reliability and long lifetime.
- > Industrial control and factory automation: the key areas will be energy efficiency and sustainability.
- > Healthcare: challenges are related to workflow efficiency, integration of diagnosis and treatment, quality assurance.
- > Internet of Things: the increased amount of data available, as well as safety and security issues, will need to be processed.

# **TECHNICAL** innovation

- > Cost of the system design: EMC<sup>2</sup> multi-core architecture, with its development ecosystem of improved programmability, dynamic runtime environment and tool support, eases design and analysis.
- > Effort and time required for revalidation and recertification of systems after making changes: through architectural support for mixed-critical applications, the early consideration of non-functional properties and the holistic integration of development and validation/certification activities in the EMC<sup>2</sup> interoperability framework.
- > Management of increased complexity: EMC<sup>2</sup> multi-core architecture and the development ecosystem reduce software complexity and leverage the benefits of module consolidation.
- > Cross-sector reusability of Embedded Systems devices and architecture platforms: through crosssector embedded hardware architecture including a dynamic runtime environment.





PROJECT COORDINATOR		START	
Werner Weber		1 April 2	2014
INSTITUTION		DURATIO	N
Infineon		36 mon	ths
EMAIL werner.weber@ir	fineon.com	TOTAL IN € 93.92	<b>VESTMENT</b> M
WEBSITE		PARTICIP	ATING ORGANISATIONS
www.artemis-emc2.eu		100	
		NUMBER	OF COUNTRIES

ABB AB Aicas GmbH Airbus Defence and Space GmbH -Cassidian Airbus Defence and Space GmbH - EADS Alenia Aermacchi S.p.A Alten Sweden AB AMBAR Telecomunicaciones S.L. ArcCore AB Arcticus Systems AB Austrian Institute of Technology AVL List GmbH AVL Software and Functions GmbH **Blueice BVBA** BMW AG Brno University of Technology CEA Chalmers University of Technology Consorzio Interuniversitario Nazionale per l'Informatica CRF, Centro Ricerche Fiat Critical Software Danfoss Power Electronics A/S Denso Automotive Deutschland GmbH Elektrobit Automotive GmbH EnSilica ERICSSON AB eVision Systems GmbH Fornebu Consulting AS Fraunhofer IESE Freescale Semiconductor Czech Republic Frequentis AG Harokopio University of Athens HI-Iberia Ingenieria y Proyectos INESC ID Lisboa Infineon Technologies AG Infineon Technologies Austria AG Infineon Technologies UK Ltd INRIA Institute of Microelectronic Applications s.r.o. Instituto Superior de Engenharia do Porto Instituto Tecnológico de Informática Integrasys S.A. Ixion Industry & Aerospace SL

Kompetenzzentrum - Das virtuelle Fahrzeug, Forschungsgesellschaft GmbH **KTH Royal Institute of Technology** Lulea University of Technology Magillem Design Services MBDA Italia S.p.A. NXP Semiconductors NXP Semiconductors Germany GmbH OFFIS Philips Medical Systems Nederland B.V. Politecnico di Torino Quobis Networks SL Riga Technical University **Rockwell Collins France** SELEX ES S.p.A. Seven Solutions S.L. Siemens AG SILKAN S.A. Simula Research Laboratory AS Stichting Imec Nederland Sundance Multiprocessor Technology Ltd Swedish Institute of Computer Science AB SYSGO AG Sysgo s.r.o. Systematic Systemite AB

Thales Research and Technology The Irish software engineering research Centre The University of Manchester TNO TomTom International BV TTTech Computertechnik AG United Technologies Research Centre Ireland Ltd. Universita degli Studi dell'Aquila Universita degli Studi di Genova University of Bristol University of Oslo University of Technology Delft
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AV ČR, v.v.i.
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Visure Solutions S.L.
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